

\*\*\*\*NOTE: MEMORY CHIPS CAN BE INSTALLED IN EITHER OF TWO WAYS, IT IS UP TO YOU WHICH OF THE TWO METHODS YOU EMPLOY.

#### INSTALLATION OF MEMORY CHIPS: (OPTION A)

STEP 1. AFTER MAKING SURE THAT CHIP PAD AREA IS FREE FROM FLUX AND LOCTITE-422 RESIDUE, USE A SHARP TOOTHPICK AND PLACE A VERY SMALL AMOUNT OF FRESH LOCTITE-422 IN THE CENTER OF THE CHIP PAD AREA. THE SIZE OF THE DROP OF GLUE SHOULD BE NO GREATER THAN 1/16 IN. IN DIAMETER. REFER TO FIGURE M-3.

STEP 2. USING A PAIR OF TWEEZERS, POSITION THE REPLACEMENT CHIP OVER THE GLUE AND GENTLY LOWER ONTO THE GLUE, MAKING SURE THAT THE CHIP IS CENTERED ON THE PADS. REFER TO FIGURE M-4. AFTER CHIP IS ON THE BOARD, PRESS DOWN FIRMLY FOR SEVERAL SECONDS TO ALLOW GLUE TO SET AND TO MAKE SURE THE CHIP IS FLUSH AGAINST THE PADS.

STEP 3. AFTER GLUE HAS SET, APPLY A LIBERAL AMOUNT OF FLUX TO PADS. USING THE 600 DEGREE IRON, TOUCH THE IRON AGAINST ANY PAD, AS CLOSE AS POSSIBLE TO THE CHIP WITHOUT TOUCHING THE CHIP, AND APPLY SOME SOLDER. WAIT FOR THE SOLDER TO FLOW AND WICK UP UNDER THE CHIP.

STEP 4. REPEAT STEP 3 UNTIL ALL PADS ARE SOLDERED.

\*\*\*\* NOTE: IT IS NOT NECESSARY TO FLOW THE SOLDER ALL THE WAY UP THE PLATED PORTION OF THE LEGLESS LEAD ON THE VERTICAL SIDES OF THE CHIP. AS LONG AS THE LEADS WERE TINNED ON THE UNDERSIDE OF THE CHIP AND AT LEAST PARTIALLY UP THE VERTICAL SIDES, ALLOWING FOR A MINIMAL FILLET OF SOLDER BETWEEN THE PADS AND CHIP SIDES, YOU SHOULD HAVE NO PROBLEMS. ALSO, MAKE SURE THAT THE SOLDER FLOW HAS ENOUGH TIME TO WICK UP UNDER THE CHIP WHILE REMEMBERING NOT TO BURN A HOLE IN THE BOARD. HAVE FUN. REFER TO FIGURE M-6.

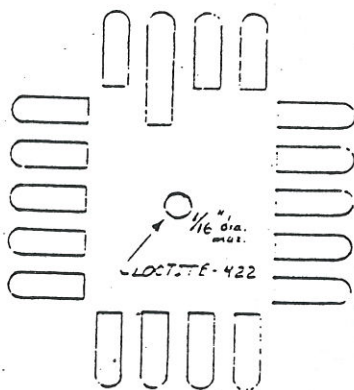


FIG. M-3

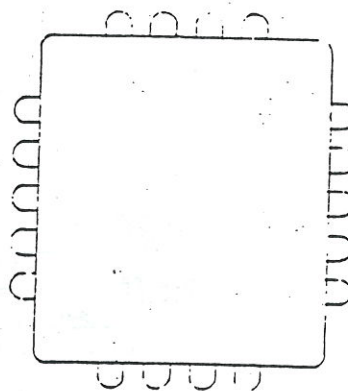


FIG. M-4